Claims

What is claimed is:

1. A method for assembling an optical disk apparatus comprising the steps of:

assembling an optical pickup device comprising:

a housing,

a laser diode mounted in the housing,

an objective lens disposed at one face of the housing, and

first and second short-cutting terminals disposed at different faces of the housing and in parallel between terminals of the laser diode, wherein in a first state of assembling, the first short-cutting terminal is shorted by a solder;

inspecting the optical pickup device in a second state of assembling in which the solder is removed from the first short-cutting terminal;

after inspecting, short-cutting the second short-cutting terminal by applying a solder thereon;

mounting the inspected optical pickup device into a setting apparatus; and

removing the solder applied on the second short-cutting terminal.

2. The method of claim 1, wherein assembling the optical pickup device comprises:

disposing the second short-cutting terminal at a face opposite to a face where the objective lens is disposed, and

disposing the first short-cutting terminal at a face different from the face where the objective lens and the second short-cutting terminal are disposed.

3. The method of claim 1, wherein the first short-cutting terminal is disposed on a side surface of the housing, and wherein the second short-cutting terminal is disposed on a rear surface of the housing.

4. The method of claim 1, wherein an optical pickup and the laser diode are disposed within the housing.

5. The method of claim 1, wherein the housing is rectangular.

6. The method of claim 1, the optical pickup device further comprising:

a flexible wiring substrate disposed along a side surface and a rear surface of said housing, wherein the first and second short-cutting terminals are disposed on the flexible wiring substrate.

7. The method of claim 1, wherein the first and second short-cutting terminals each comprise a semiconductor solder land that face each other.

8. The method of claim 1, wherein the first short-cutting terminal is disposed on a side surface of the housing located at a position proximate a rear surface of the housing.

9. A method for manufacturing an optical pickup device, comprising:

disposing a first short-cutting terminal on a side of a housing of the optical pickup device;

disposing a second short-cutting terminal on a different side of the housing, wherein the first short-cutting terminal and the second short-cutting terminal are disposed in parallel and in between terminals of a laser diode of the optical pickup device;

selectively applying a solder to the first short-cutting terminal during a first stage of the manufacturing;

removing the solder from the first short-cutting terminal during a second stage of the manufacturing;

selectively applying a solder to the second short-cutting terminal;

mounting the optical pickup device in a setting apparatus; and

removing the solder from the second short-cutting terminal.

10. The method of claim 9, wherein the first short-cutting terminal is disposed on a side surface of the housing, and wherein the second short-cutting terminal is disposed on a rear surface of the housing.